

Docket No.: \_\_\_\_\_

## DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought on the invention entitled STACKED

SEMICONDUCTOR PACKAGE AND FABRICATING METHOD THEREOF

\_\_\_\_\_, the  
specification of which

[ ☒ ] is attached hereto [ ☐ ] was filed on \_\_\_\_\_ as Application Serial No. \_\_\_\_\_ and was  
amended on \_\_\_\_\_ (if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by  
any amendment referred to above.

I acknowledge the duty to disclose information which is known to me to be material to patentability in accordance with Title 37, Code of  
Federal Regulations, Section 1.56(a).

I hereby claim foreign priority or provisional application benefits under Title 35, United States Code, Section 119 of any foreign  
application(s) for patent or inventor's certificate, or provisional application(s) listed below and have also identified below any foreign  
application for patent or inventor's certificate, or provisional application(s) having a filing date before that of the application on which priority  
is claimed:

Prior Foreign Application(s) or U.S. Provisional Application(s):			Priority Claimed	
<u>Number</u>	<u>Country</u>	<u>Day/Month/Year</u>	<u>Yes</u>	<u>No</u>
<u>7745/1999</u>	<u>Korea</u>	<u>09/03/1999</u>	<u>x</u>	

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s) listed below and, insofar as  
the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by  
the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title  
37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT  
international filing date of this application:

Prior U. S. Application(s):		<u>Status: Patented, Pending, Abandoned</u>
<u>Serial No.</u>	<u>Filing Date</u>	

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are  
believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are  
punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements  
may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s): Daniel Y.J. Kim, Registration No. 36,186 and Mark L. Fleshner, Registration No. 34,596; Mark G. Toohey, Registration No. 35,392; Carl R. Wesolowski, Registration No. 40,372, John C. Eisenhart, Registration No. 38,128, Rene A. Vasquez, Registration No. 36,647, all of

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with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and all future correspondence should be addressed to them.

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Full name of sole or first inventor: Sun-Dong KIM  
Inventor's signature: Sun Dong Kim Date: 08/12/99  
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Citizenship: Republic of Korea  
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Full name of joint inventor(s):  
Inventor's signature: Date:  
Residence:  
Citizenship:  
Post Office Address:

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Full name of joint inventor(s):  
Inventor's signature: Date:  
Residence:  
Citizenship:  
Post Office Address: